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**Qualification Results Summary**

**of AD9833WBRMZ-REEL**

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| **QUALIFICATION PLAN** | | | |
| **Test** | **Specification** | **Sample Size** | **Results** |
| Electrostatic Discharge  *Field-Induced Charged*  *Device Model* (corner pins) | JEDEC*JS-002* | 3/voltage | Pass ±750V |
| Electrostatic Discharge  *Field-Induced Charged*  *Device Model* (all pins) | JEDEC*JS-002* | 3/voltage | Pass ±750V |
| Electrostatic Discharge  *Human Body Model* | JEDEC *JESD22-A114* | 3/voltage | Pass ±2500V |
| Latch-Up | JEDEC *JESD78* | 1 x 15 | Pass |
| Highly Accelerated Stress Test (HAST)1 | JEDEC *JESD22-A110* | 3 x 82 | Pass |
| Unbiased Highly Accelerated Stress Test (uHAST)1 | JEDEC *JESD22-A118* | 3 x 82 | Pass |
| High Temperature Operating Life  (HTOL)1 | JEDEC *JESD22-A108* | 1 x 82 | Pass |
| High Temperature Storage Life  (HTS) | JEDEC *JESD22-A103* | 1 x 82 | Pass |
| Temperature Cycle Test  (TCT)1 | JEDEC *JESD22-A104* | 3 x 82 | Pass |
| Wire Bond Pull | MIL-STD-883 M2011 | 3 x 5 | Pass |
| Solder Heat Resistance (SHR)1 | JEDEC *J-STD-020* | 3 x 16 | Pass |
| Solderability | JEDEC *J-STD-002* | 1 x 15 | Pass |

1Preconditioned per JEDEC J-STD-020 Level 3